



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of:

Chen et al.
Serial No: 09/115,444
Filed: 07/14/98
For: HIGH DENSITY INTERNAL BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE

Docket No.: TI-25912
Examiner: Foster, D.
Art Unit: 2841

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T.O.S.
Kye
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TC 2800 MAIL ROOM

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

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OFFICE OF PETITIONS

Dear Sir:

Please make the references listed on the enclosed PTO-1449 of record under 37 C.F.R. 1.56, 1.97, and 1.98 in the patent application identified above. Copies of the listed references are enclosed.

Respectfully submitted,

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